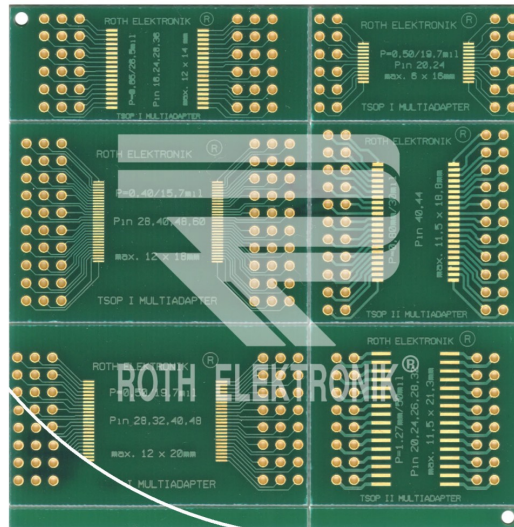


Multiadapter - SMD TSOP I/II



RE900



- FR4 EPOXY fibre-glass FR4 1.50 mm double-sided 35 µm CU (pth)
- solder and component side with chemical NI/AU surface and solder stop mask
- pitch spacings: 0.40 mm (15.7 mil); 0.50 mm (19.7 mil); 0.65 mm (26.5 mil); 0.80 mm (30 mil); 1.27 mm (50 mil)
- hole dia Ø 1.00 mm
- adaption board for 14 different SMD TSOP I and 7 different SMD TSOP II chips
- prescratched rated break point for the separation of individual moduls from the board
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- size: 72.60 x 76.20 mm

Modul-No	Type	Pitch	Pin/Quantity	Size max./mm
RE900-01	TSOP I	0.40	28,40,48,60	12 x 18
RE900-02	TSOP I	0.50	28,32,40,48	12 x 20
RE900-03	TSOP I	0.50	20,24	6 x 16
RE900-04	TSOP I	0.65	16,24,28,36	12 x 14
RE900-05	TSOP II	0.80	40,44	11.5 x 18.8
RE900-06	TSOP II	1.27	20,24,26,28,32	11.5 x 21.3